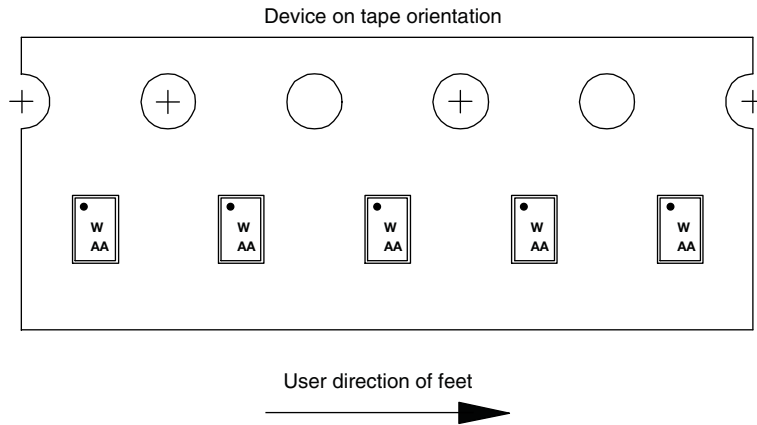


Device Orientation for WCSP 2 x 3 and WCSP 2 x 4

DEVICE ORIENTATION	
PACKAGE	METHOD
WCSP 2 x 3 0.5 mm pitch, 0.250 mm bump height	T2
WCSP 2 x 4 0.4 mm pitch, 0.208 mm bump height	T2



Revision control of this drawing is maintained through Document Control, Pack Specification-PACK-0023-xx